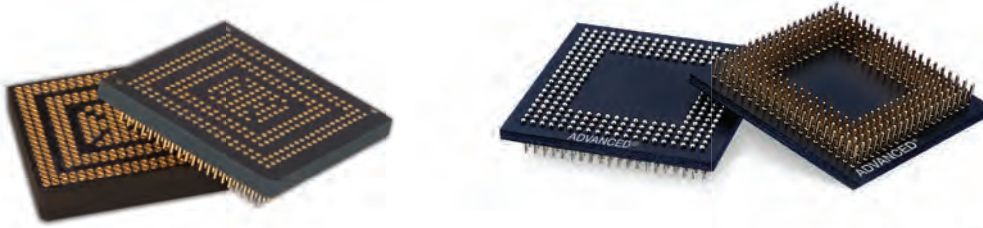


BGA Socketing Systems

Our Ball Grid Array Socket Adapter Systems and Flip-Top™ BGA Test Sockets offer a reliable method for socketing BGA, LGA, and CSP devices in validation, test, and production applications.

- Compact designs match IC device footprint.
- Proprietary solder ball terminals offer process yields equivalent to direct device attach.
- Available in tape and reel packaging for automated assembly.



Board to Board Connectors

Proven reliability and design flexibility provide effective results for even the most demanding board to board and mezzanine board applications.

- Thru-hole and surface mount designs available.
- High quality screw-machined terminals offer reliable electrical/mechanical interconnect.
- Mezza-pede® SMT Connectors offer a mated height under 3mm.



**Ultra-thin
removable
terminal carrier
(.005"/0.13mm)**



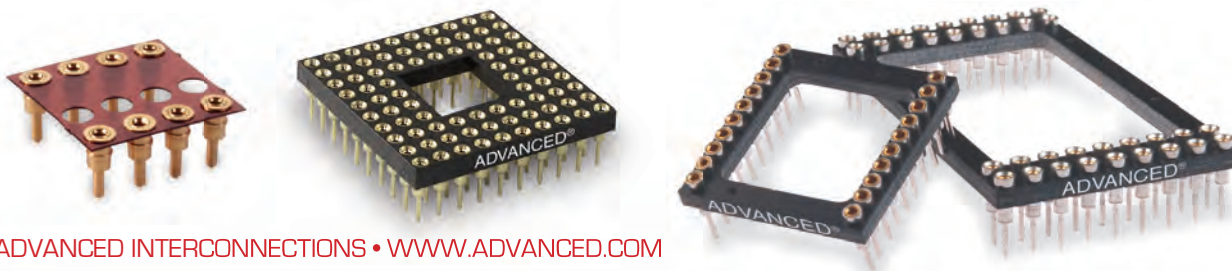
**Optional solder
preforms eliminate
wave soldering**



IC Sockets and Adapters

Advanced offers a wide variety of IC Sockets and Adapters for virtually any package configuration including PGA, DIP, and SIP, as well as application-specific designs such as Image Sensor Sockets.

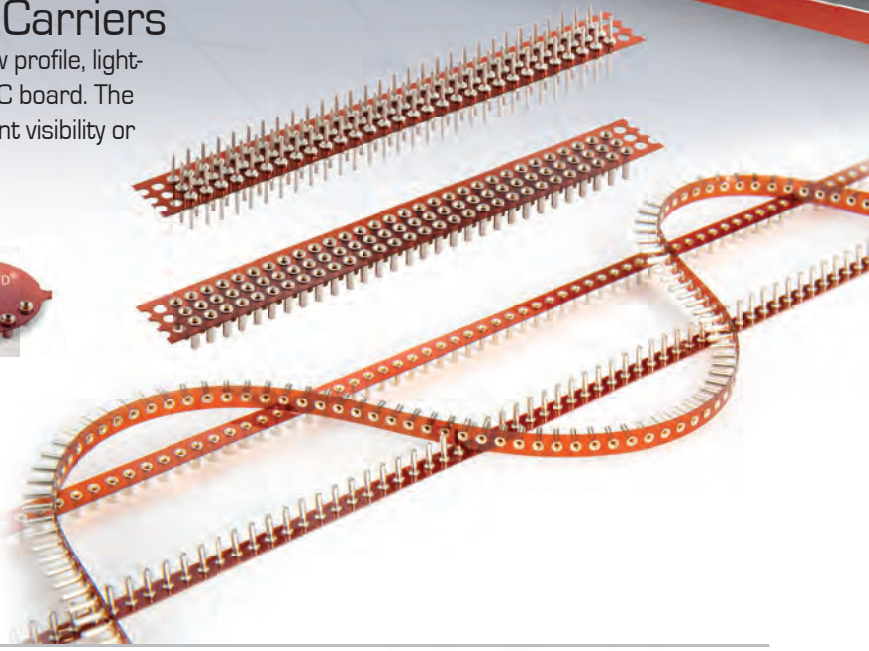
- Insulator options include FR-4, molded, and our proprietary Peel-A-Way® Removable Terminal Carriers.
- Peel-A-Way® Carriers can be easily customized with multiple terminal types.



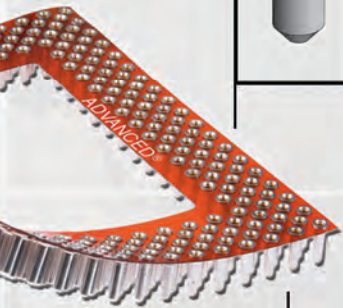
Peel-A-Way® Removable Terminal Carriers

Peel-A-Way® Removable Terminal Carriers provide an ultra-low profile, light-weight solution for loading socket or adapter terminals on a PC board. The flexible insulator can be easily removed for complete solder joint visibility or left in place for added stability.

- Replaces hand-loading operations
- Enables complete solder joint inspection
- Easily customized with multiple terminal styles



Multi-finger contacts suitable for high vibration applications

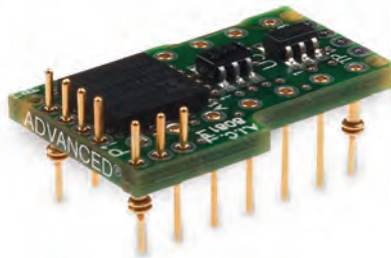


Screw-machined terminals for durability

Package Conversion Adapters

Advanced® Adapters are designed to your specifications for IC package conversion, test, emulation, and development applications.

- Standard designs include SOIC to DIP and PLCC to PGA adapters.
- Custom designs can include device enhancements or corrections by adding passive components.



Terminals & Test Jacks

Precision screw-machined terminals are the foundation of our high quality sockets, adapters, and connectors, and also available for loose socket and pin applications.

- Standard and customized designs including options such as solder preforms, test point pins, special plating, and individual tape and reel packaging.
- Complete line of standard and semi-custom EMC® (Electronic Molding Corporation) brand insulated and non-insulated Terminals and Test Jacks are available.

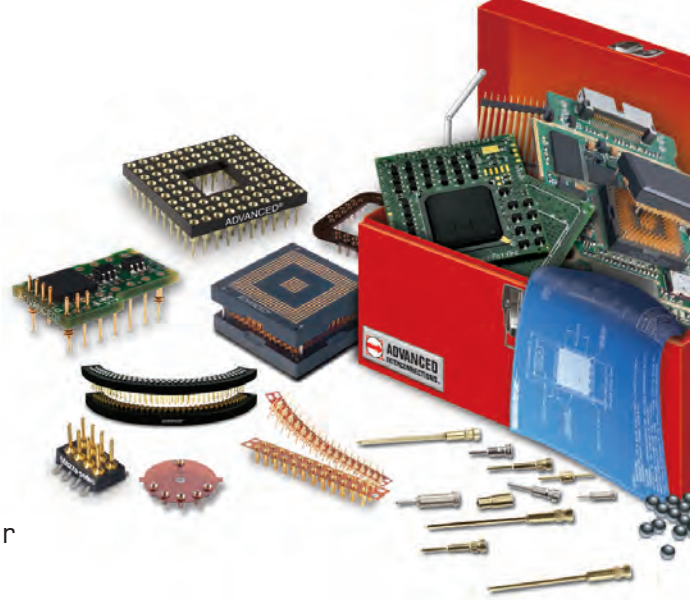


Solving Your Design Challenges

Our experienced technical staff works hands-on with customers to provide application design assistance, drawing from a well-stocked tool box of interconnect technology. If a standard terminal or insulator fits the requirements, we'll recommend it. If not, we'll combine standard and modified components from our tool box to create a customized solution that precisely fits your application. Either way, the result is practical and cost-effective.

Our Tool Box Includes:

- More than 500 screw-machined terminal designs
- Extensive tooling capability for custom shapes
- CNC equipment for economical prototype volumes
- A variety of material and plating options



Advanced Interconnections is a leading designer and manufacturer of innovative interconnect solutions for electronic applications around the world. We specialize in IC sockets, package conversion adapters, and PC board connectors, produced with the highest quality screw-machined terminals and multi-finger contacts for superior reliability.

Visit advanced.com or request a catalog for complete product specifications.

ISO
9001



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